

MBS (STD GPP) bridge rectifiers(MBS6) comparison report

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Checked by Owen Wang
Approved by Quayer Chen
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Reversion for A

Comparison report (MBS6)

Material information summary:

	Old	New	Result
Mold compound material type(Non-Green)	EME-1100SA	Cancel	
Mold compound material type(Halogen Free)	EME-EK110G	EME-EK110G EME-EK1800G	

Production Part Approval - Material, Performance Test Results Discrete Semiconductor Component Qualification Plan

Customer P/N :	MBS6	Product Engineer :	Reyn
Customer Spec. # :	N/A	General Specification :	
Supplier Name :	Taiwan Semiconductor Corp.	Supplier Manufacturing Site :	YEW
Supplier Generic P/N :	MBS 0.8Amps bridge rectifiers	Required PPAP Submission Date :	18-Jul-12
Supplier Internal P/N :	MBS2 thru MBS10	Family Type :	STD GPP
Reason for Qual. :	Add second source with molding compound		

Item	Test	Test Condition	Exceptions	Est. Start	Est. Comp.	# Lots	S.S.	Remarks
1	Electrical Test	Electrical characterization	@25°C	17-Jul-12	17-Jul-12	ALL	616	ACC
2	External Visual	Inspect device construction, marking and workmanship	N/A	18-Jul-12	18-Jul-12	ALL	616	ACC
3	Parametric Verification	Electrical characterization	@25/150°C	19-Jul-12	19-Jul-12	1	25	ACC
4	Pre-conditioning	Per specification	N/A	19-Jul-12	28-Jul-12	1	231	ACC
5	Intermittent Operating Life	On/5min, Off/5min	2520cycles	26-Jul-12	3-Aug-12	1	77	ACC
6	H.T.R.B.	80% Rated VR (T=150°C)	168hrs	18-Jul-12	26-Jul-12	1	77	ACC
7	Autoclave	Ta = 121 ± 2°C 15Psig	96hrs	18-Jul-12	22-Jul-12	1	77	ACC
8	Moisture Resistance	Ta = 85 ± 2°C, R.H = 85 ± 5%	168hrs	23-Jul-12	31-Jul-12	1	77	ACC
9	Low Temperature Storage	Ta = -55 ± 3°C	168hrs	23-Jul-12	31-Jul-12	1	77	ACC
10	High Temperature Storage	Ta = 150(+10/-0)°C	168hrs	23-Jul-12	31-Jul-12	1	77	ACC
11	Soldering Heat	Ta = 260 ± 5°C	10secs	23-Jul-12	23-Jul-12	1	30	ACC
12	Temperature Cycle	-55°C/15Min, 150°C/15Min, 25°C/5Min (Transfer)	100cycles	18-Jul-12	25-Jul-12	1	77	ACC
13	Forward Surge Test	8.3ms Single Half sine-wave Superimposed on Rated Load	@25°C	23-Jul-12	23-Jul-12	1	10	ACC
14	Solderability	Ta = 245 ± 5°C	5secs	23-Jul-12	23-Jul-12	1	10	ACC
15	DPA	Per specification	N/A	31-Jul-12	1-Aug-12	1	2	ACC
16								
17								

Comment :

Prepared by :	Haiyen Liu	Approved by :	Hejun Cui
Date :	2-Aug-12	Date :	3-Aug-12
Title :	Hi-rel supervisor	Title :	QA leader